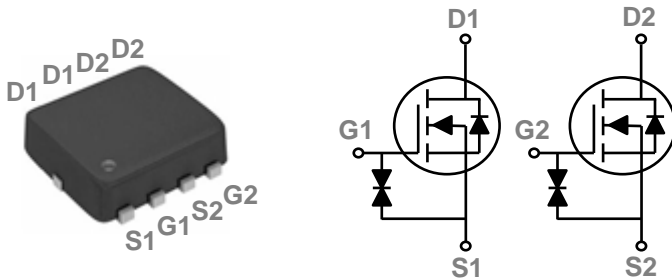


20V Dual N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK3x3 Dual Pin Configuration



BVDSS	RDSON	ID
20V	12mΩ	30A

Features

- 20V,30A, $R_{DS(ON)} = 12m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- ESD Protection Diode Embedded
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR
- Li-Battery Protection

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	30	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	19	A
I_{DM}	Drain Current – Pulsed ¹	120	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	26	W
	Power Dissipation – Derate above 25°C	0.21	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.8	$^\circ\text{C}/\text{W}$



FTK2210VNN

Electrical Characteristics (T_J =25 °C , unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25 °C , I _D =1mA	---	0.02	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V , V _{GS} =0V , T _J =25 °C	---	---	1	uA
		V _{DS} =16V , V _{GS} =0V , T _J =125 °C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±10V , V _{DS} =0V	---	---	±10	uA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =10A	8	10	12	mΩ
		V _{GS} =4.2V , I _D =10A	8	10.1	12.2	mΩ
		V _{GS} =3.7V , I _D =9A	8	10.3	12.5	mΩ
		V _{GS} =3.0V , I _D =9A	8.5	10.7	13.2	mΩ
		V _{GS} =2.5V , I _D =8A	9	11.4	14.5	mΩ
		V _{GS} =1.8V , I _D =8A	10	15	20	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	0.3	0.6	1	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	2	---	mV/°C
g _{fs}	Forward Transconductance	V _{DS} =10V , I _S =5A	---	12	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =10V , V _{GS} =4.5V , I _D =5A	---	16.9	26	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	1.1	3	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	4	7	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =10V , V _{GS} =4.5V , R _G =25Ω I _D =1A	---	6.8	13	ns
T _r	Rise Time ^{2, 3}		---	20	38	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	41.8	79	
T _f	Fall Time ^{2, 3}		---	13.2	25	
C _{iss}	Input Capacitance	V _{DS} =10V , V _{GS} =0V , F=1MHz	---	1020	1480	pF
C _{oss}	Output Capacitance		---	160	240	
C _{rss}	Reverse Transfer Capacitance		---	110	160	
R _g	Gate resistance	V _{GS} =0V , V _{DS} =0V , F=1MHz	---	2	4	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current	---	---	30	A
I _{SM}	Pulsed Source Current		---	---	60	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25 °C	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

Typical Performance Characteristics

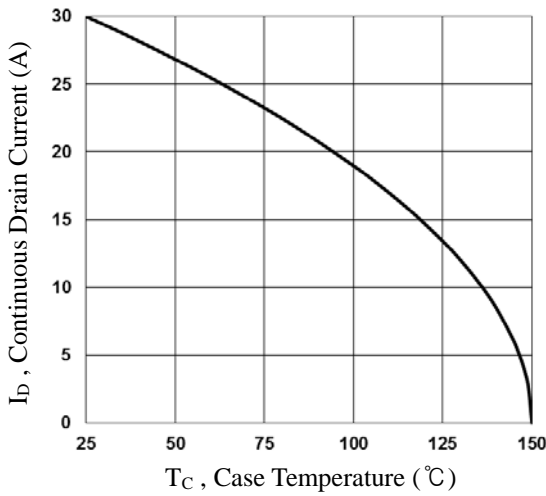


Fig.1 Continuous Drain Current vs. T_C

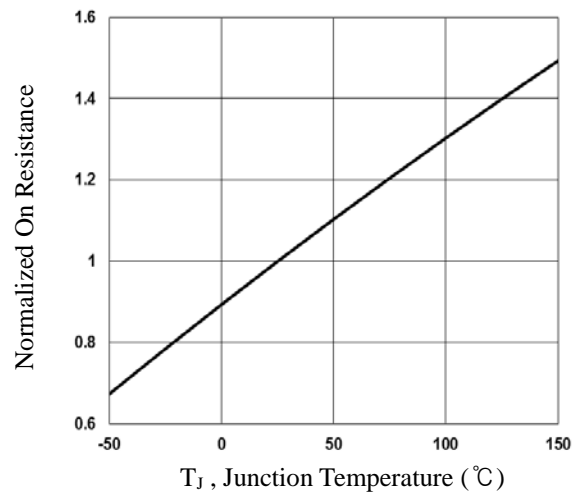


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

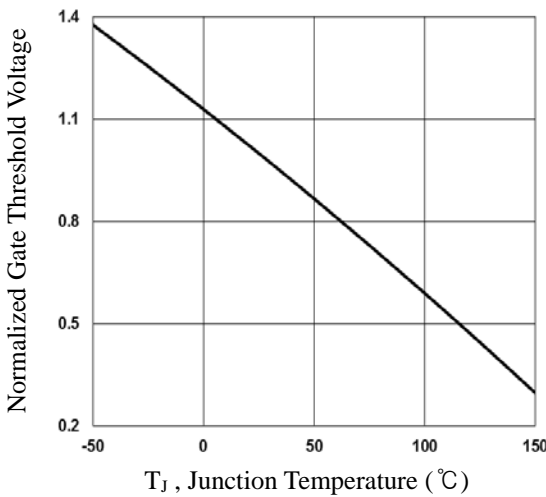


Fig.3 Normalized V_{th} vs. T_J

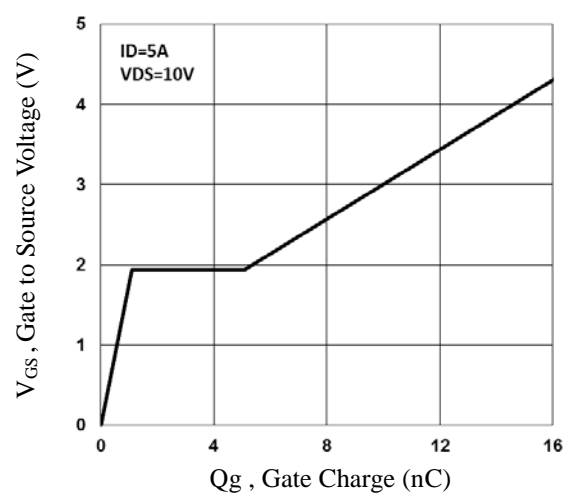


Fig.4 Gate Charge Waveform

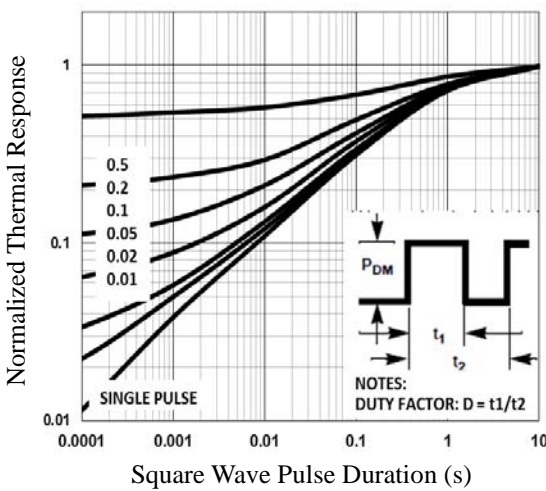


Fig.5 Normalized Transient Response

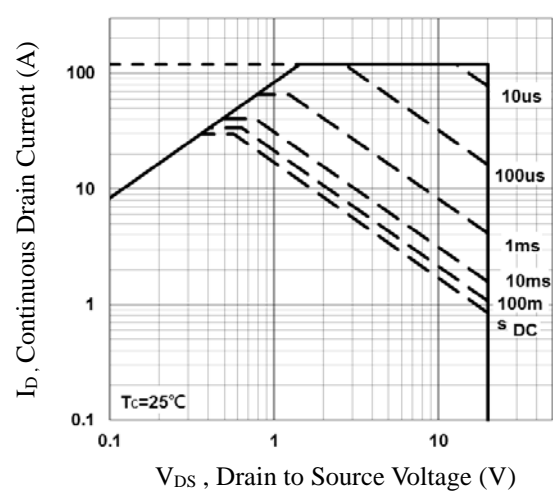


Fig.6 Maximum Safe Operation Area

Typical Performance Characteristics(Con.)

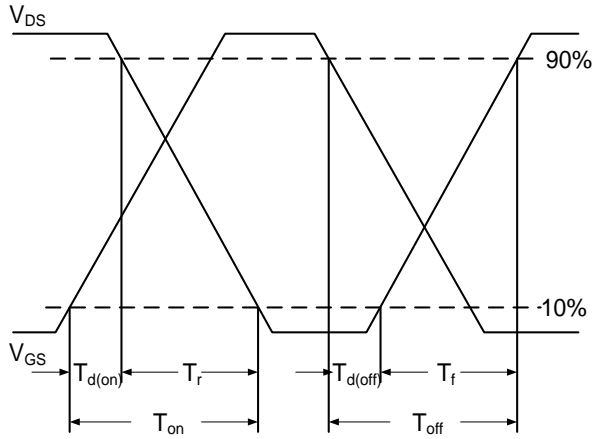


Fig.7 Switching Time Waveform

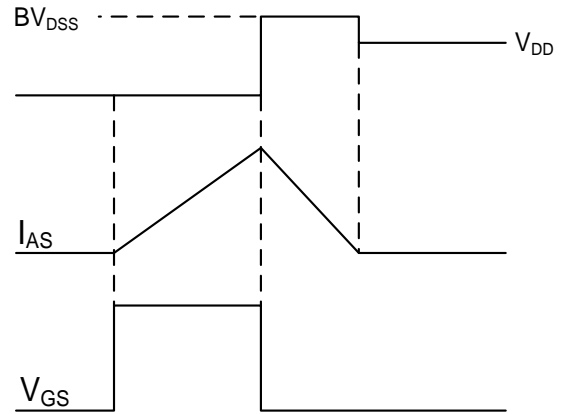
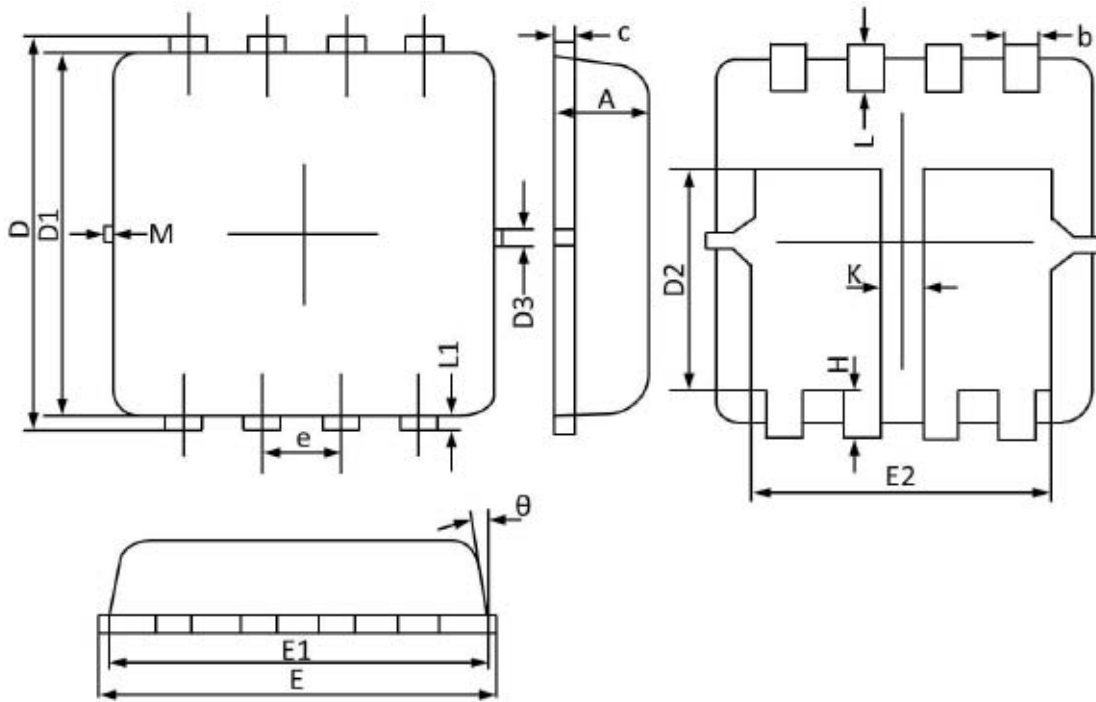


Fig.8 EAS Waveform

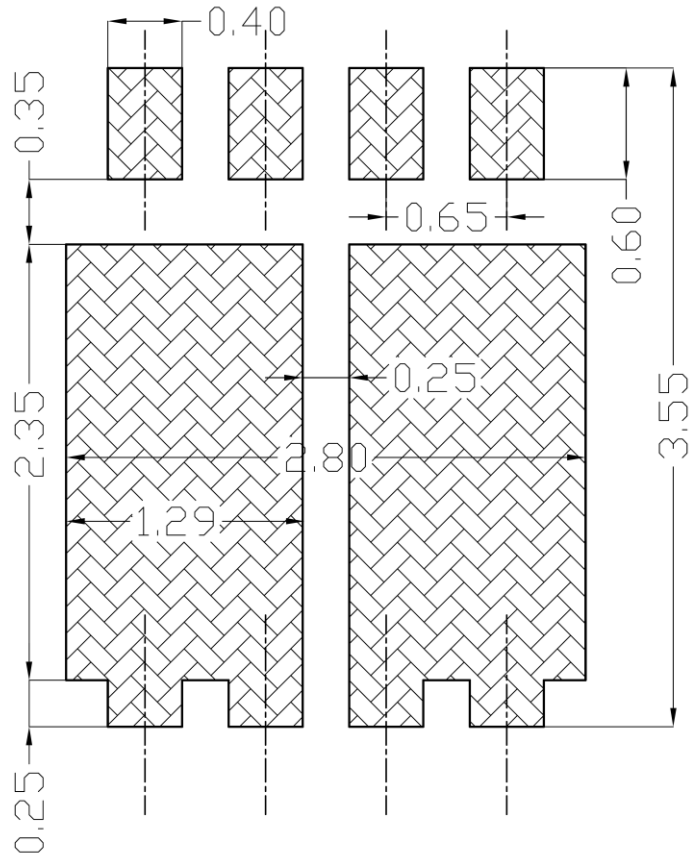
PPAK3x3 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.670	0.880	0.026	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.150	3.550	0.124	0.140
D1	3.000	3.300	0.118	0.130
D2	1.500	2.000	0.059	0.079
D3	0.130	0.200	0.005	0.008
E	3.100	3.500	0.122	0.138
E1	3.000	3.200	0.118	0.126
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L1	0.130 REF		0.005 REF	
K	0.300 REF		0.012 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	



PPAK3X3 Dual RECOMMENDED LAND PATTERN



unit : mm